

Title (en)

METHOD FOR LINKING A CHIP AND A SUBSTRATE

Title (de)

VERFAHREN ZUM VERBINDEN EINES CHIPS UND EINES SUBSTRATS

Title (fr)

PROCEDE DE CONNEXION D'UNE PUCE ET D'UN SUBSTRAT

Publication

EP 1861872 A1 20071205 (DE)

Application

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Priority

EP 2005003170 W 20050324

Abstract (en)

[origin: WO2006099885A1] The invention relates to a method for linking a chip (10) and a substrate (20), which comprises initially providing an adhesive (30) including conducting particles. The chip (10) and the substrate (20) each comprises at least one contact surface (12, 14, 16, 22, 24, 26) on a corresponding face (18). The adhesive (30) is applied to one face of the substrate (20) or to one face of the chip (10), and the chip (10) and the substrate (20) are brought into contact with each other while aligning the contact surfaces. The arrangement is impinged upon with pressure in such a manner that the adhesive is locally densified in the area between the contact surfaces of the chip and the substrate and the conducting particles adhere to the contact surfaces. The adhesive (30) is finally cured.

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Citation (search report)

See references of WO 2006099885A1

Citation (examination)

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